

ON Semiconductor®

FDS8433A

Single P-Channel 2.5V Specified MOSFET

General Description

This P-Channel enhancement mode power field effect transistors is produced using ON Semiconductor's proprietary, high cell density, DMOS technology. This very high density processis especially tailored to minimize on-state resistance and provide superior switching performance.

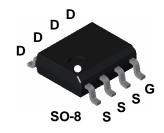
Applications

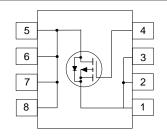
- Load switch
- DC/DC converter
- Battery protection

Features

• -5 A, -20 V. R
$$_{DS(on)}$$
 = 0.047 Ω @ V $_{GS}$ = -4.5 V $_{DS(on)}$ = 0.070 Ω @ V $_{GS}$ = -2.5 V

- Fast switching speed.
- High density cell design for extremely low R_{DS(on)}.
- High power and current handling capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

| Symbol | Parameter | | FDS8433A | Units |
|-----------------------------------|--|-----------|-------------|-------|
| V _{DSS} | Drain-Source Voltage | | -20 | V |
| V _{GSS} | Gate-Source Voltage | | <u>±</u> 8 | V |
| I _D | Drain Current - Continuous | (Note 1a) | -5 | А |
| | - Pulsed | | -50 | |
| P _D | Power Dissipation for Single Operation | (Note 1a) | 2.5 | W |
| | | (Note 1b) | 1.2 | |
| | | (Note 1c) | 1 | |
| T _J , T _{stg} | Operating and Storage Junction Temperatu | re Range | -55 to +150 | ∘C |

Thermal Characteristics

| $R_{\theta^{JA}}$ | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 50 | °C/W |
|-------------------|---|-----------|----|------|
| $R_{\theta^{JC}}$ | Thermal Resistance, Junction-to-Case | (Note 1) | 25 | °C/W |

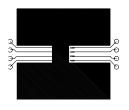
Package Outlines and Ordering Information

| Device Marking | Device | Reel Size | Tape Width | Quantity |
|----------------|----------|-----------|------------|------------|
| FDS8433A | FDS8433A | 13'' | 12mm | 2500 units |

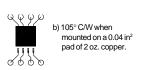
| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|---|---|---|------|-------|-------|---------------|
| Off Char | acteristics | | | | | |
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} = 0 V, I _D = -250 μA | -20 | | | V |
| BVpss ΔT, | Breakdown Voltage Temperature Coefficient | I_D = -250 μ A, Referenced to 25°C | | -25 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$ | | | -1 | μΑ |
| I _{GSSF} | Gate-Body Leakage Current, Forward | $V_{GS} = 8 \text{ V}, V_{DS} = 0 \text{ V}$ | | | 100 | nA |
| I_{GSSR} | Gate-Body Leakage Current, Reverse | $V_{GS} = -8 \text{ V}, V_{DS} = 0 \text{ V}$ | | | -100 | nA |
| On Char | acteristics (Note 2) | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$ | -0.4 | -0.6 | -1 | V |
| $\frac{\Delta V_{GS(th)}}{\Delta T_{,l}}$ | Gate Threshold Voltage Temperature Coefficient | $I_D = -250 \mu\text{A}$, Referenced to 25°C | | 4 | | mV/°C |
| R _{DS(on)} | Static Drain-Source | $V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}$ | | 0.036 | 0.047 | Ω |
| | On-Resistance | $V_{GS} = -4.5 \text{ V}, I_D = -5 \text{ A}, T_J = 125^{\circ}\text{C}$ | | 0.050 | 0.085 | Ω |
| l _{nc} , | On-State Drain Current | $V_{GS} = -2.5 \text{ V}, I_D = -4.3 \text{ A}$ $V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$ | -25 | 0.047 | 0.070 | <u>Ω</u> A |
| g _{FS} | Forward Transconductance | $V_{DS} = -5 \text{ V}, I_D = -5 \text{ A}$ | 20 | 16 | | S |
| | | 1 105 - 3 1, 10 - 3 11 | | | ļ | |
| Dynamic C _{iss} | Characteristics Input Capacitance | V _{DS} = -10 V, V _{GS} = 0 V, | | 1130 | | pF |
| Coss | Output Capacitance | f = 1.0 MHz | | 480 | | рF |
| Crss | Reverse Transfer Capacitance | | | 120 | | рF |
| | · | | | 120 | | рі |
| - | ng Characteristics (Note 2) | IV 40V I 4 A | | _ | 40 | |
| t _{d(on)} | Turn-On Delay Time | $V_{DD} = -10 \text{ V}, I_{D} = -1 \text{ A},$ $V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$ | | 8 | 16 | ns |
| t _r | Turn-On Rise Time | VGS = -4.5 V, NGEN = 0 | | 23 | 37 | ns |
| t _{d(off)} | Turn-Off Delay Time | | | 260 | 360 | ns |
| t _f | Turn-Off Fall Time |), 5), I 5 | | 90 | 125 | ns |
| Q _g | Total Gate Charge | $V_{DS} = -5 \text{ V}, I_{D} = -5 \text{ A}, V_{GS} = -5 \text{ V},$ | | 20 | 28 | nC |
| Q _{gs} | Gate-Source Charge | | | 2.8 | | nC |
| Q_{gd} | Gate-Drain Charge | | | 3.2 | | nC |
| Drain-Sc | purce Diode Characteristics and | | ı | ı | -2.1 | I . |
| Is | | Irce Diode Forward Current Itage | | | | l A |

Notes:

^{1:} R_{BJA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 50° C/W when mounted on a 1 in² pad of 2 oz. copper.



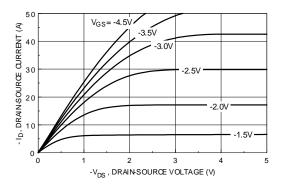


c) 125° C/W on a minimum mounting pad of 2 oz. copper.

Scale 1: 1 on letter size paper

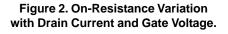
2: Pulse Test: Pulse Width $\leq\!300~\mu\text{s},$ Duty Cycle $\leq\!2.0\%$

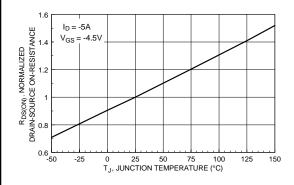
Typical Characteristics



2 1.8 POSCON 1.4 POSCO

Figure 1. On-Region Characteristics.





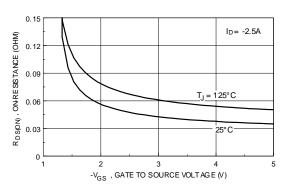
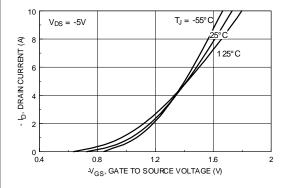


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



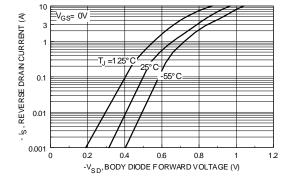
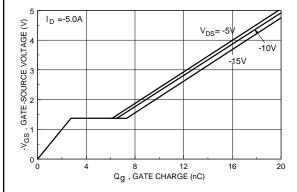


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



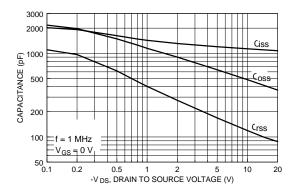
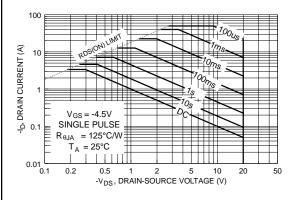


Figure 7. Gate-Charge Characteristics.





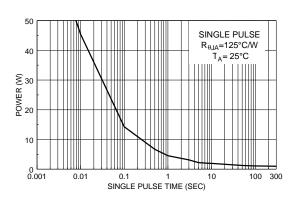


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

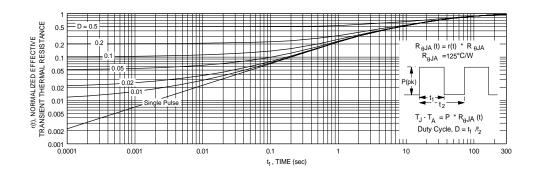


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1. Transient themal response will change depending on the circuit board design.

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